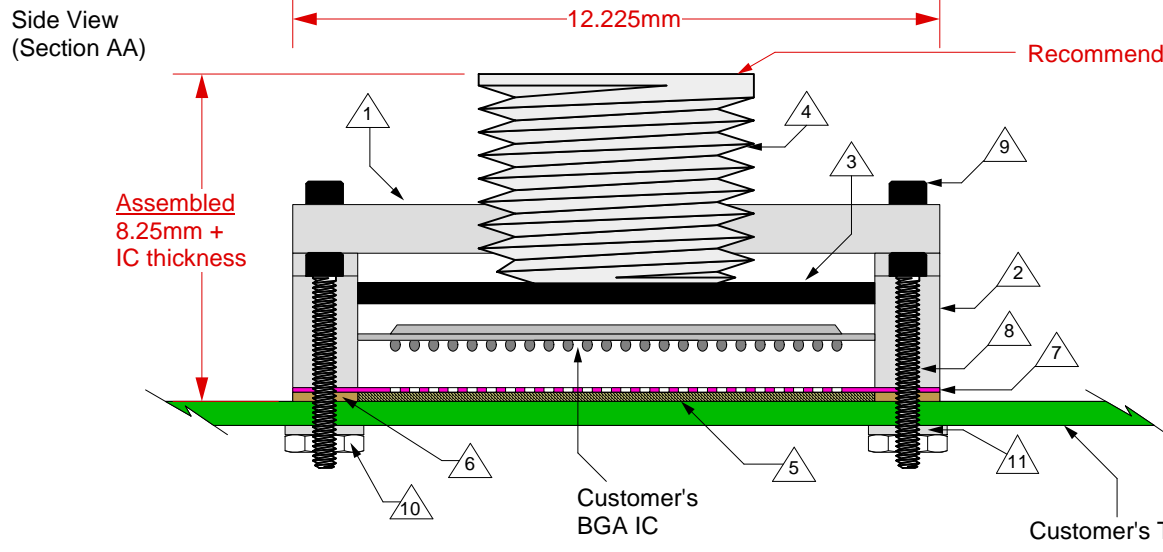
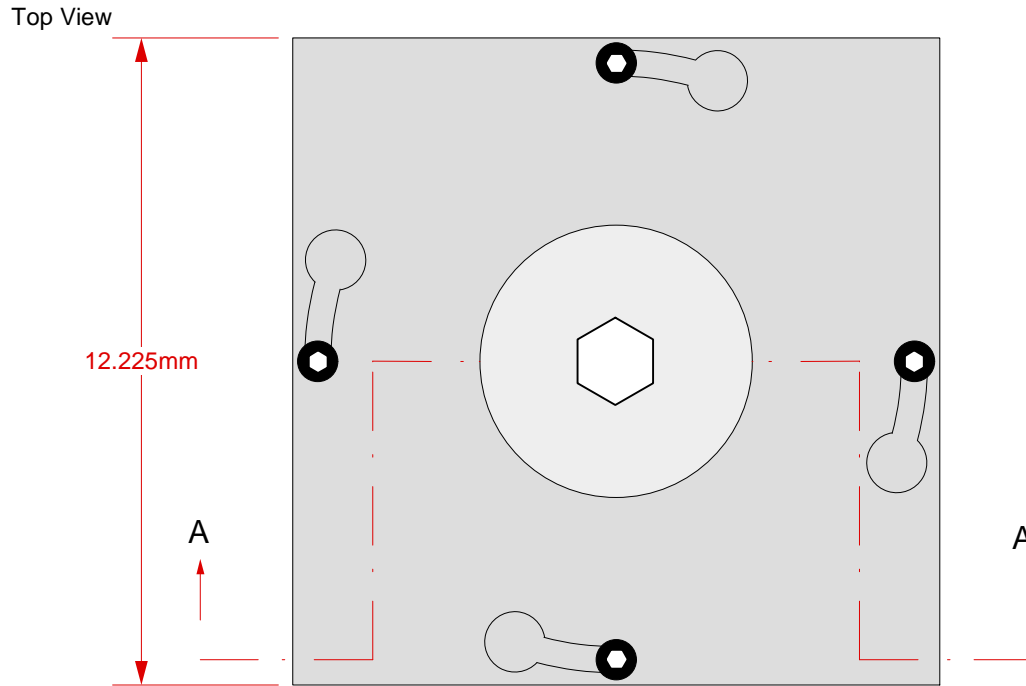



GHz BGA Socket - Direct mount, solderless



Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

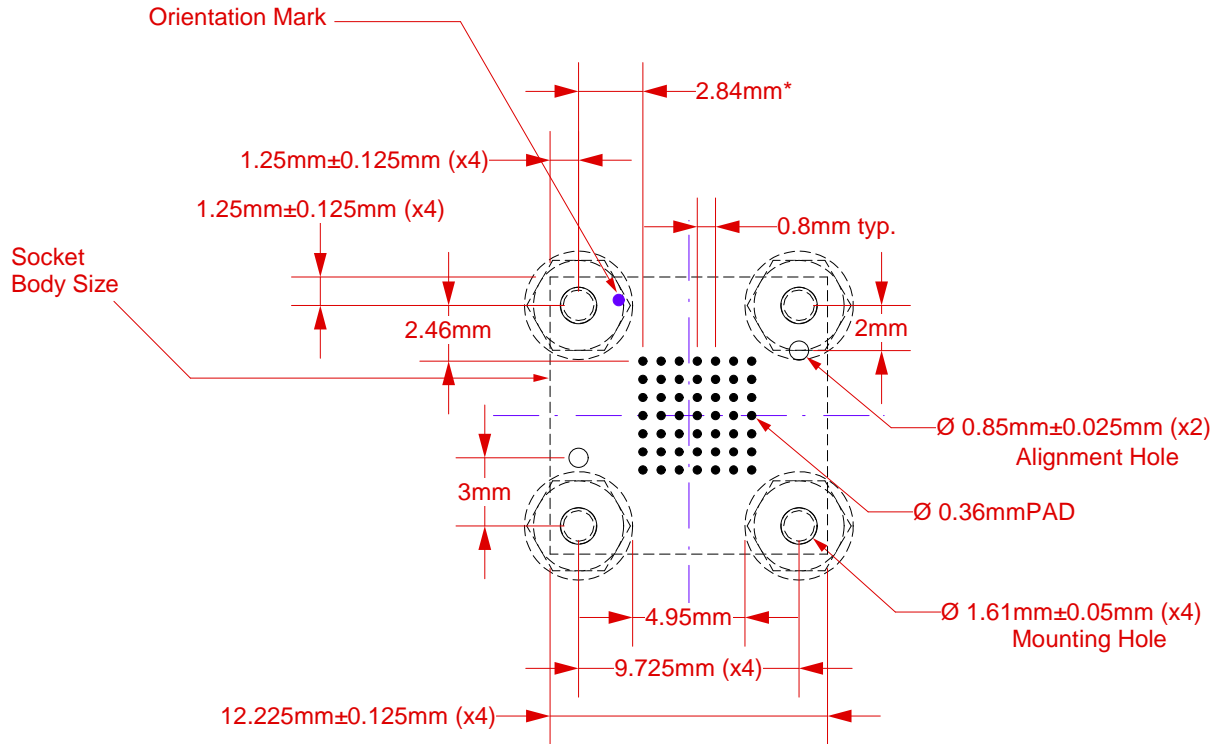
- △ 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- △ 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- △ 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- △ 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- △ 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- △ 6 Elastomer Guide: Non-clad FR4. Thickness = 0.725mm.
- △ 7 Ball Guide: Kapton polyimide.
- △ 8 Socket base screw: Socket head cap, Alloy steel with black oxide finish, 0-80 fine thread, 9.525mm long.
- △ 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- △ 10 Socket base nut: 18-8 Stainless steel, 0-80 fine thread.
- △ 11 Nylon washer: 1.73mm ID; 4.78mm OD 0.64mm thickness.

	SG-BGA-6018 Drawing	Status: Released	Scale: -	Rev: G
	© 2009 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: E Smolentseva	Date: 9/6/01	
		File: SG-BGA-6018 Dwg.mcd	Modified: 6/26/09, AE	

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**




Note: Full BGA pattern shown.
Please adjust pattern according
to individual requirements.

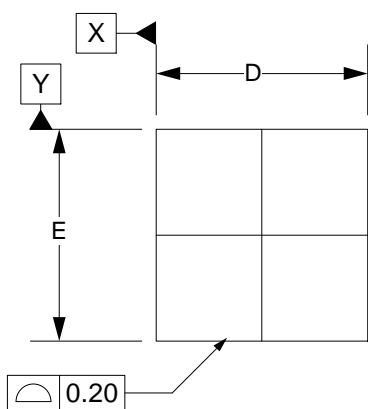
Target PCB Recommendations

Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

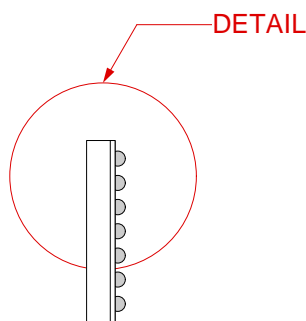
NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: $\pm 0.025\text{mm}$ [$\pm 0.001''$] unless stated otherwise.

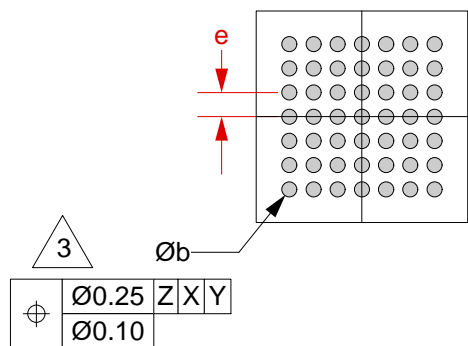
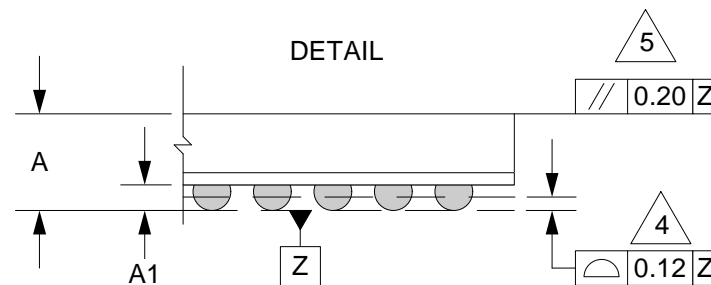
	SG-BGA-6018 Drawing	Status: Released	Scale: 3:1	Rev: G
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		File: SG-BGA-6018 Dwg.mcd	Modified: 6/26/09, AE	



TOP VIEW



SIDE VIEW




BOTTOM VIEW

- 1 Dimensions are in millimeters.
- 2 Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4 Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5 Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.5
A1	0.25	0.4
b		0.55
D	7.00 BSC	
E	7.00 BSC	
e	0.80 BSC	

Array 7x7

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	<p>Drawing: E Smolentseva</p>	<p>Date: 9/6/01</p>		
	<p>File: SG-BGA-6018 Dwg.mcd</p>	<p>Modified: 6/26/09, AE</p>		